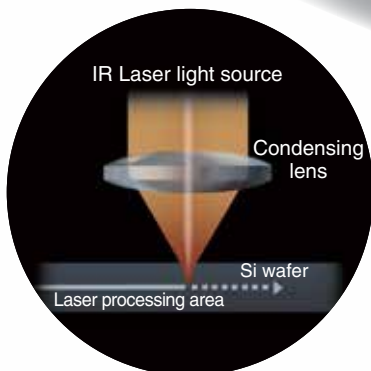




ML Dicing Machine

ML301EX WH



TOKYO SEIMITSU CO., LTD.

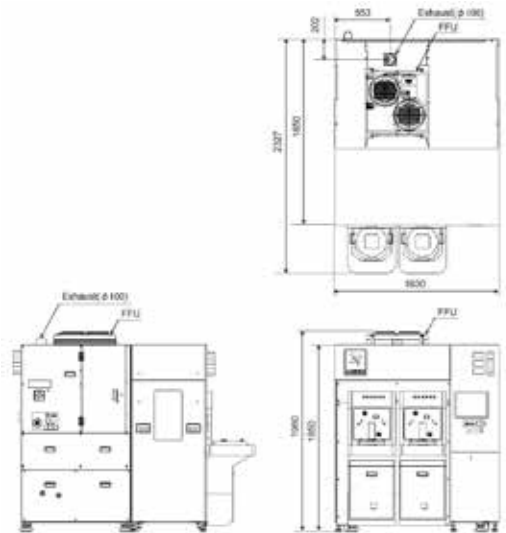
● Specifications

Applicable Wafer size	Circular wafer : 8, 12 inches diameter	
Stroke	550 mm	
X-axis	Positioning resolution	0.002 mm
	Straightness	0.0015 mm/310 mm(both horizontal and vertical)
	Stroke	427 mm
Y-axis	Positioning resolution	0.0002 mm(closed-loop control)
	Positioning accuracy	0.002 mm/310 mm
	Stroke	8.5 mm
Z-axis	Positioning resolution	0.0001 mm(closed-loop control)
	Positioning accuracy	0.001 mm/1 mm
θ-axis	Rotation range	380 deg (Max)

● Requirements

Power supply	Supply voltage : Selected from 200/220/240/380/415 VAC ± 10% 3 phase, 50 to 60 Hz.
Power consumption	7kVA max
Compressed air	Pressure : 0.5 to 0.7 MPa
N ₂ gas	Pressure : 0.5 to 0.7 MPa
Cooling water for linear motor	Pressure : 0.2 to 0.5 MPa (City water)
Dimensions	1,630 ^W x 2,327 ^D x 1,980 ^H mm (Including FFU)
Weight	2,500 kg

● External View



ACCRETECH

Japan / Head Office
Tokyo Seimitsu Co., Ltd.
2968-2, Ishikawa-machi, Hachioji-shi, Tokyo, 192-8515 Japan
TEL: (042) 642-1701 FAX: (042) 642-1798
<https://www.accretech.jp/>

● We reserve the right to change the contents of this catalog,
including product specifications, without notice when products are updated.

Please contact us.

